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**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

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In re application of: Wang et al.

Attorney Docket No.: ALTRP100/A1198

Application No.: 10/719,218

Examiner: RAO, Shrinivas H.

Filed: November 20, 2003

Group: 2814

Title: STRUCTURE, MATERIAL AND DESIGN      Confirmation No.: 3208  
FOR ASSEMBLING A LOW-K Si DIE TO  
ACHIEVE AN INDUSTRIAL GRADE  
RELIABILITY WIRE BONDING PACKAGE

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**CERTIFICATE OF EFS-WEB TRANSMISSION**

I hereby certify that this correspondence is being transmitted electronically through EFS-WEB to the Commissioner for Patents, P.O. Box 1450 Alexandria, VA 22313-1450 on March 9, 2007.

Signed: /Linda L. Quintana/  
Linda L. Quintana

**AMENDMENT C**

Mail Stop Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir:

Responsive to the Office Action mailed December 13, 2006, please consider the following remarks and amend the above-identified Application as follows.

**Amendments to the Claims** are reflected in the listing of claims, which begin on page 2 of this paper.

**Remarks/Arguments** begin on page 5 of this paper.